



US00D729089S

(12) **United States Design Patent**
Phillips et al.

(10) **Patent No.:** **US D729,089 S**

(45) **Date of Patent:** **** May 12, 2015**

(54) **SENSOR MODULE**

(71) Applicant: **Samsung Electronics Co., Ltd.**,
Suwon-si (KR)

(72) Inventors: **Sheldon George Phillips**, Glendale, CA
(US); **Frank Nuovo**, Los Angeles, CA
(US); **Tom Torfs**, Kraainem (BE);
Lindsay Brown, Mierlo (NL)

(73) Assignee: **Samsung Electronics Co., Ltd.**,
Suwon-si, Gyeonggi-do (KR)

(**) Term: **14 Years**

(21) Appl. No.: **29/491,668**

(22) Filed: **May 22, 2014**

(51) **LOC (10) Cl.** **10-04**

(52) **U.S. Cl.**
USPC **D10/103; D11/3**

(58) **Field of Classification Search**
CPC G08G 1/096883; G08G 1/096872;
G08G 1/096775; G01C 21/16; G01C 21/3688;
G01C 21/30; G01V 8/20; G01J 5/02; G01J
5/023; G01J 5/24; G01J 5/10; G01J 5/20;
G01J 5/0235; G01J 5/08; G01J 5/0853;
G01J 5/33; G01J 5/34
USPC D10/30–39, 65, 70, 78, 97, 98, 103;
D11/3; D13/173–177; D14/138 R,
D14/203.5, 247, 338–340, 344, 346, 347;
D24/167, 168
See application file for complete search history.

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Primary Examiner — Antoine D Davis

(74) *Attorney, Agent, or Firm* — McAndrews Held & Malloy, Ltd.

(57) **CLAIM**

The ornamental design for a sensor module, as shown and described.

DESCRIPTION

This application makes reference to:
U.S. Design application Ser. No. 29/491,674 filed May 22, 2014.

The above referenced application, and all of the subject matter disclosed therein, is incorporated herein by reference in its entirety.

FIG. 1 is a top left front perspective view of a sensor module showing our new design;

FIG. 2 is a rear elevation view thereof;

FIG. 3 is a front elevation view thereof;

FIG. 4 is a right side elevation view thereof;

FIG. 5 is a left side elevation view thereof;

FIG. 6 is a top plan view thereof;

FIG. 7 is a bottom plan view thereof;

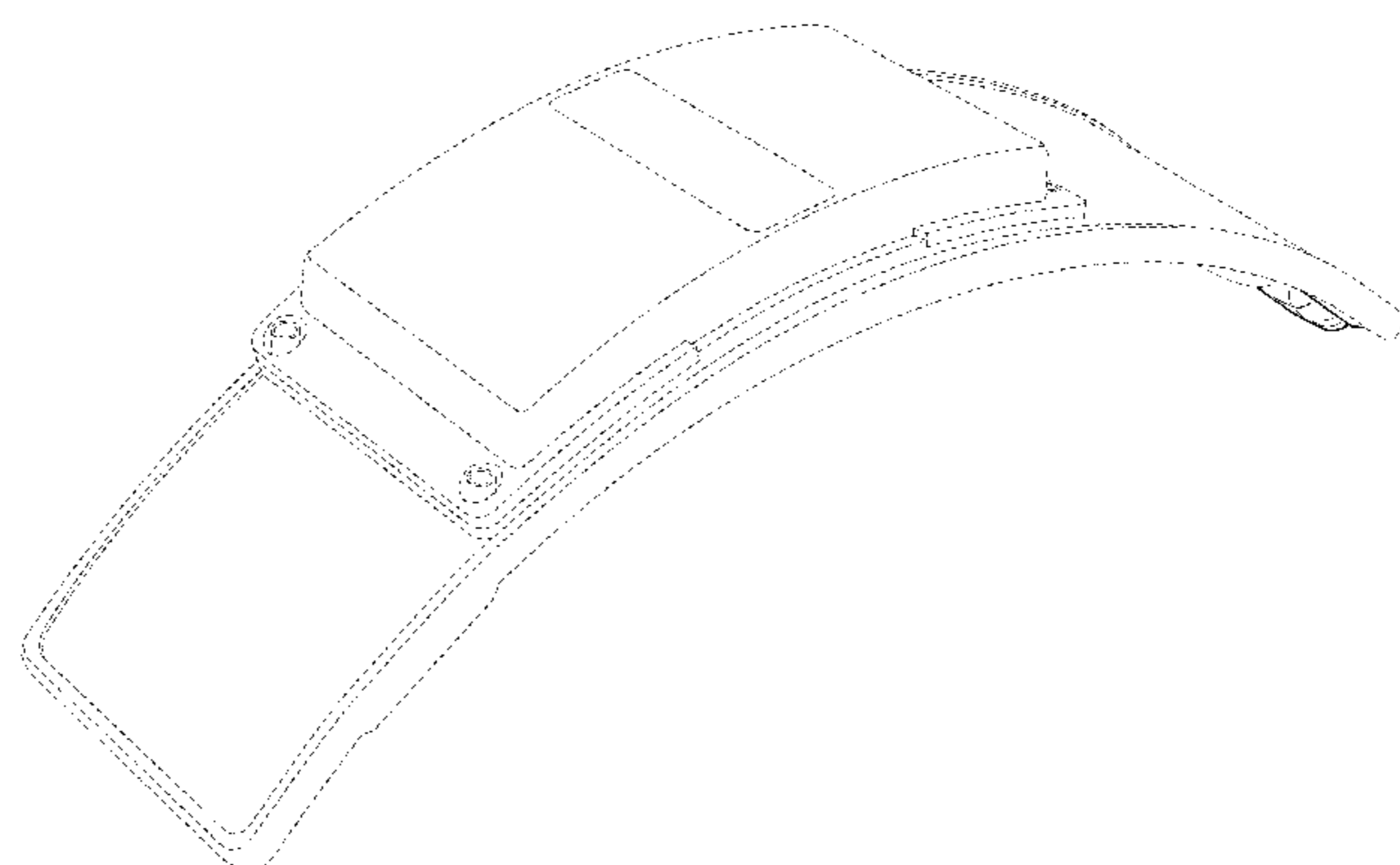
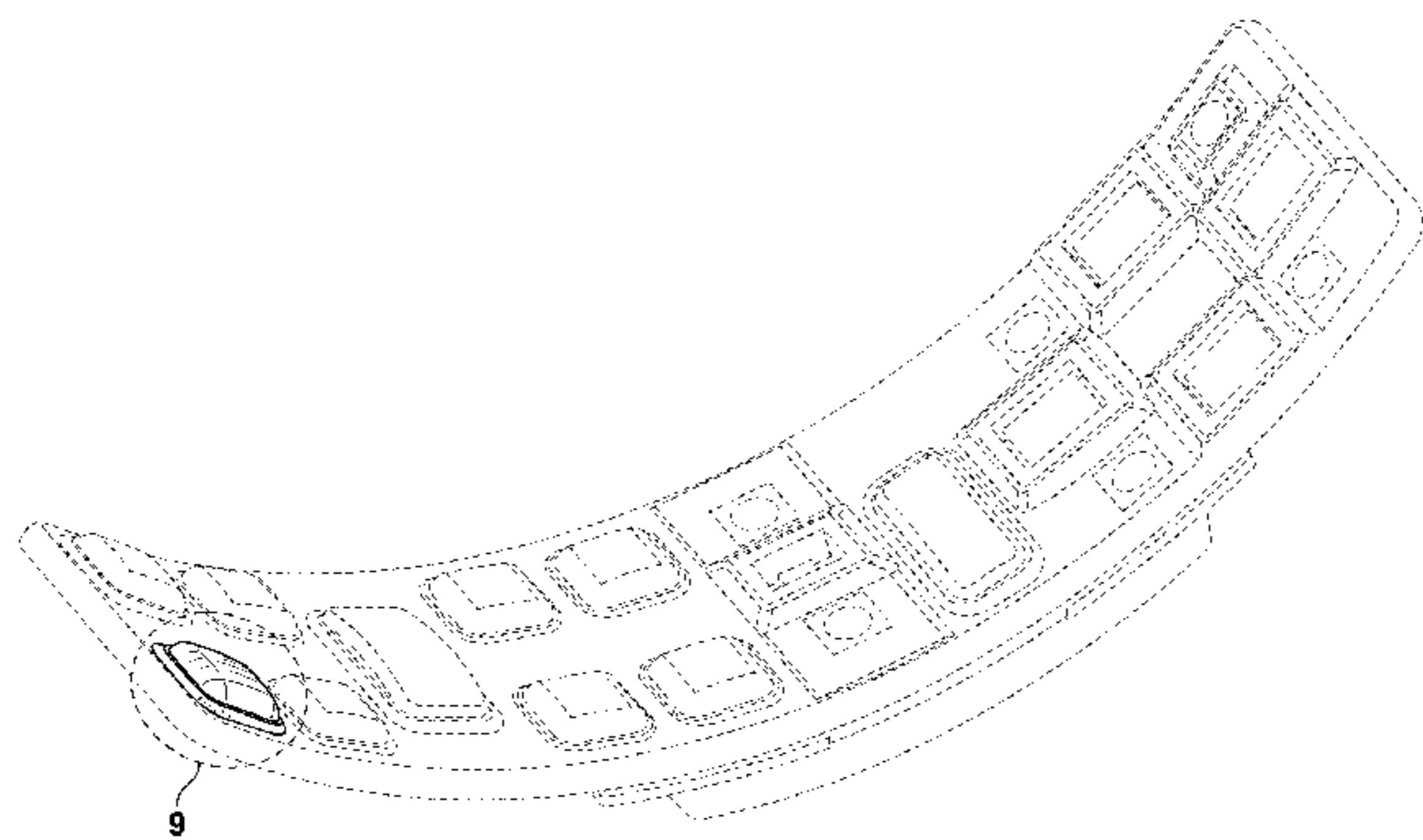
FIG. 8 is a bottom right rear perspective view thereof; and,

FIG. 9 is an enlarged view of the portion encircled in FIG. 1. The dashed broken lines are for environmental purposes only and form no part of the claimed design.

The dashed broken lines in FIG. 1 labeled with the number “9” encircle a portion of the claimed design that is illustrated in an enlargement in FIG. 9.

Any views of the sensor module that are not shown in the figures form no part of the claimed design.

1 Claim, 5 Drawing Sheets



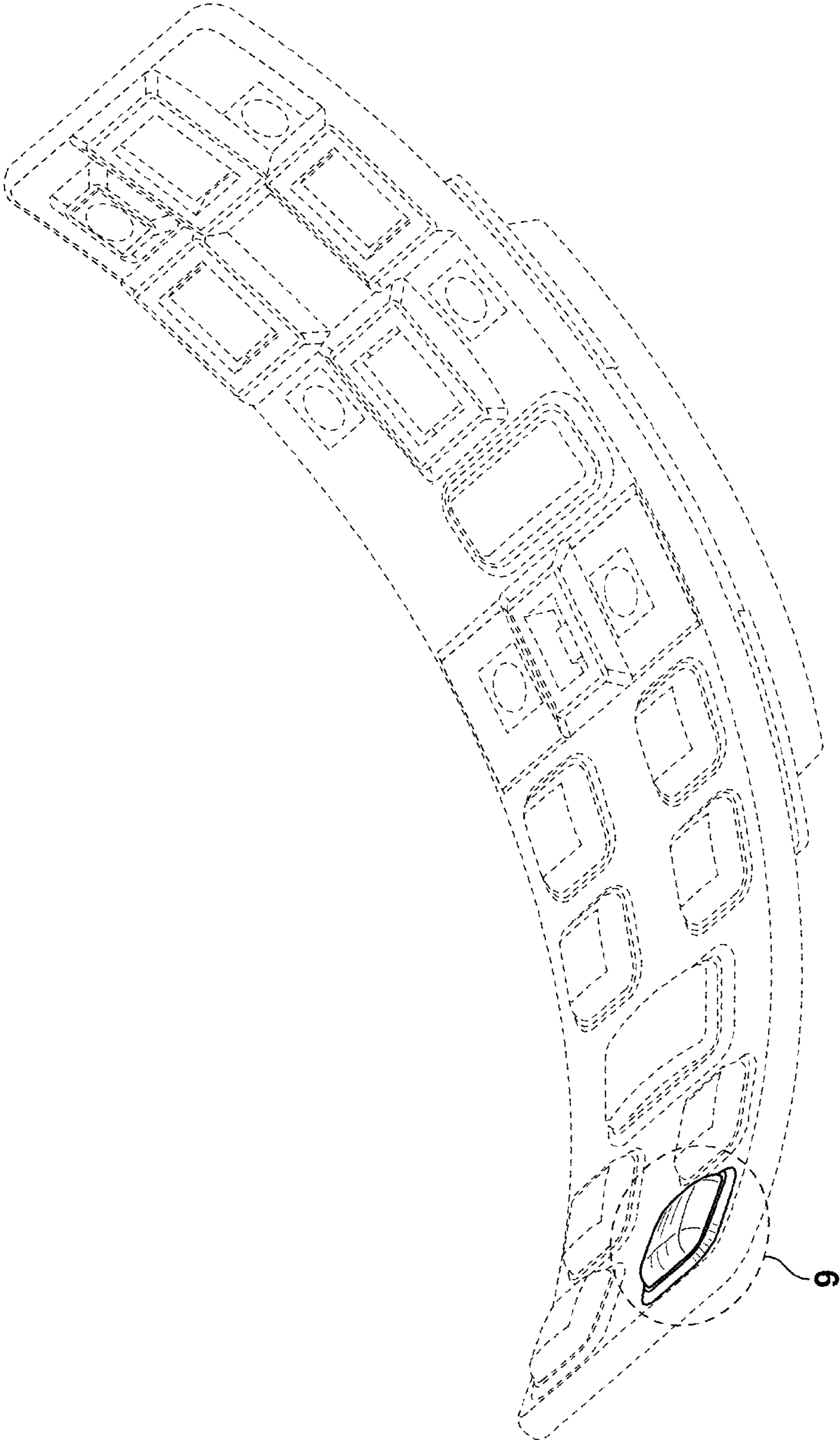


FIG. 1

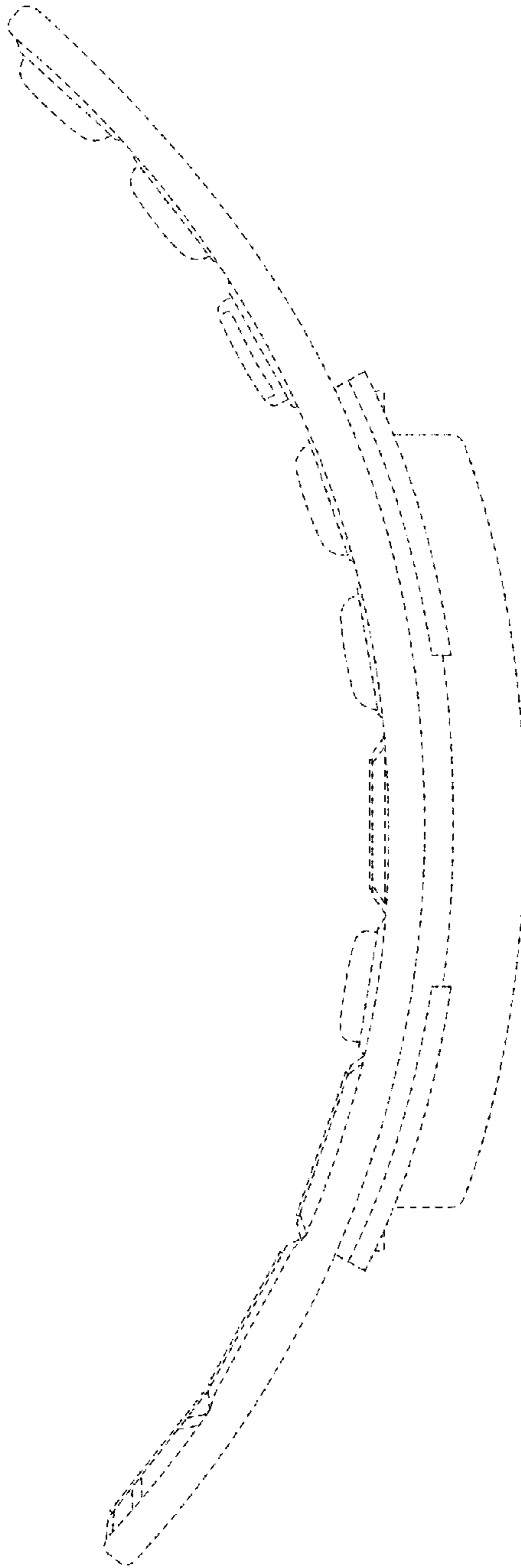


FIG. 2

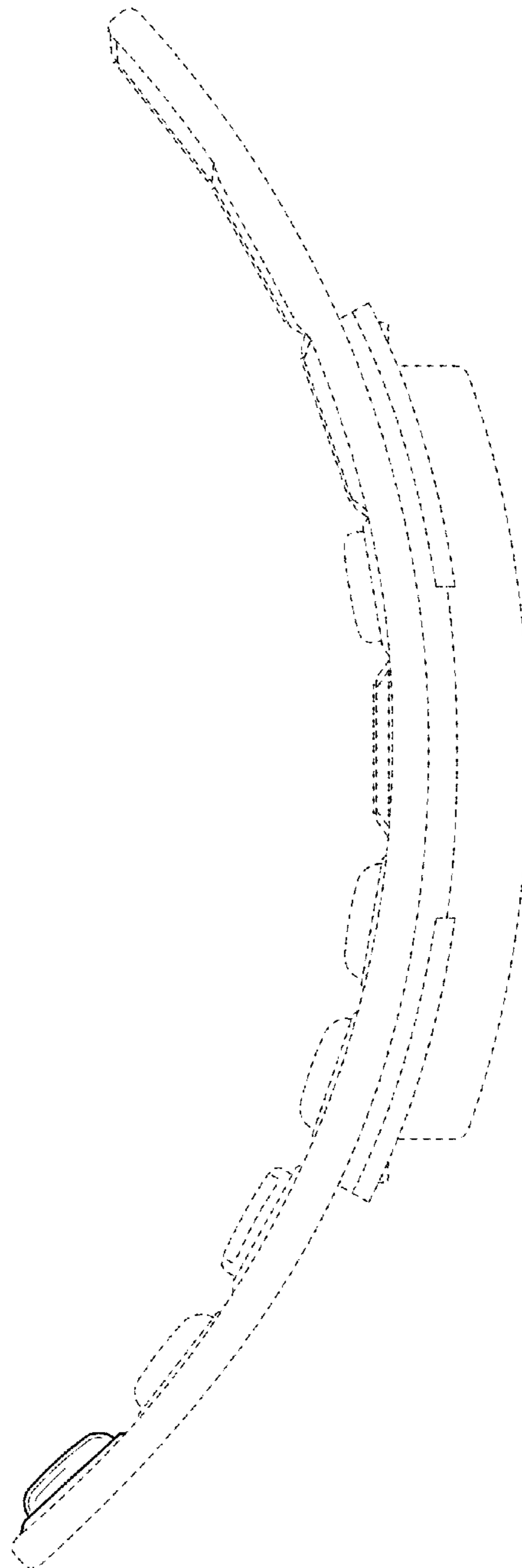


FIG. 3

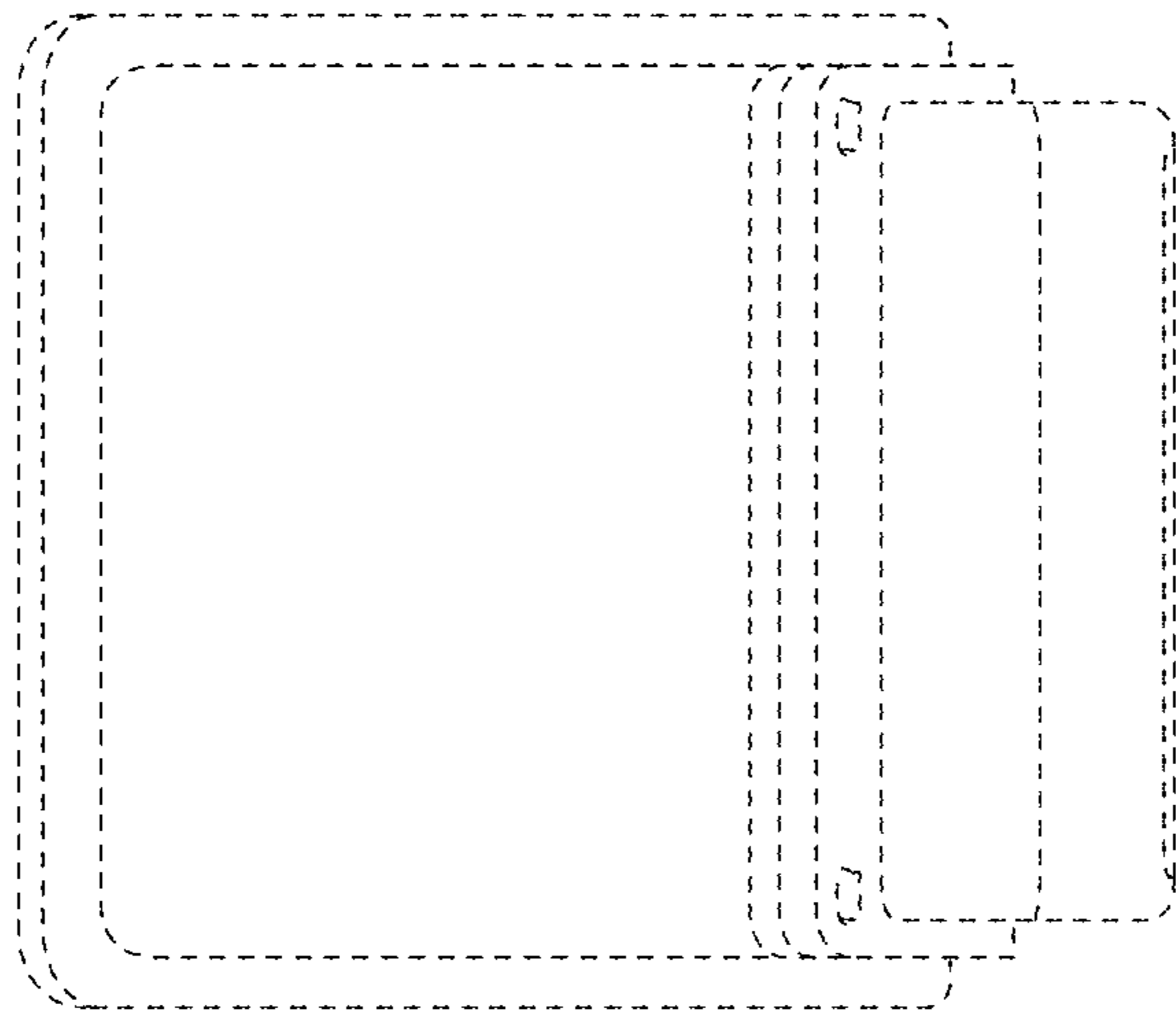


FIG. 5

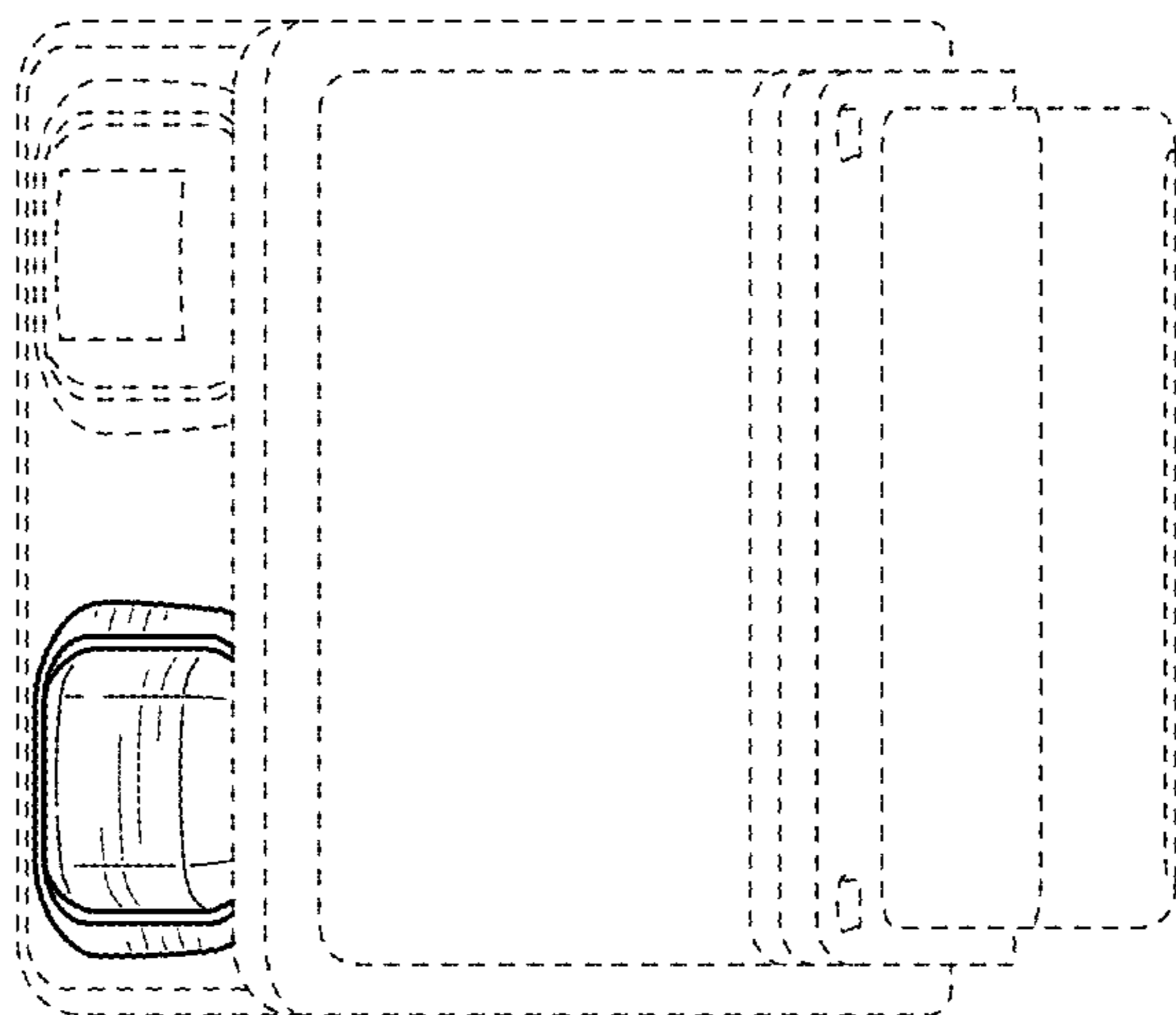


FIG. 4

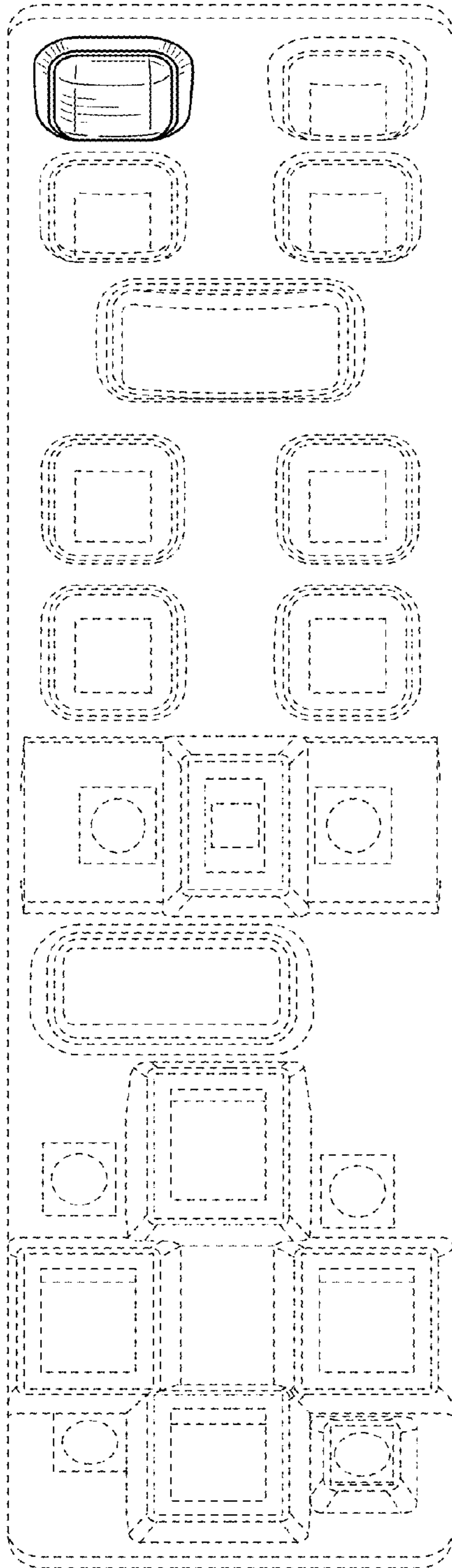


FIG. 6

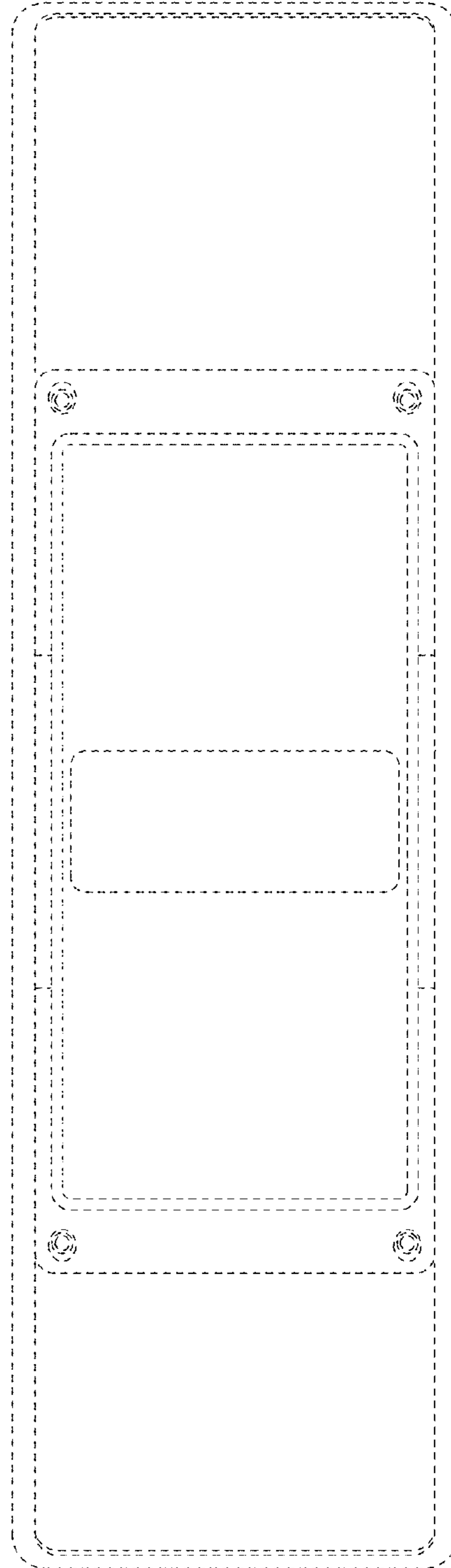


FIG. 7

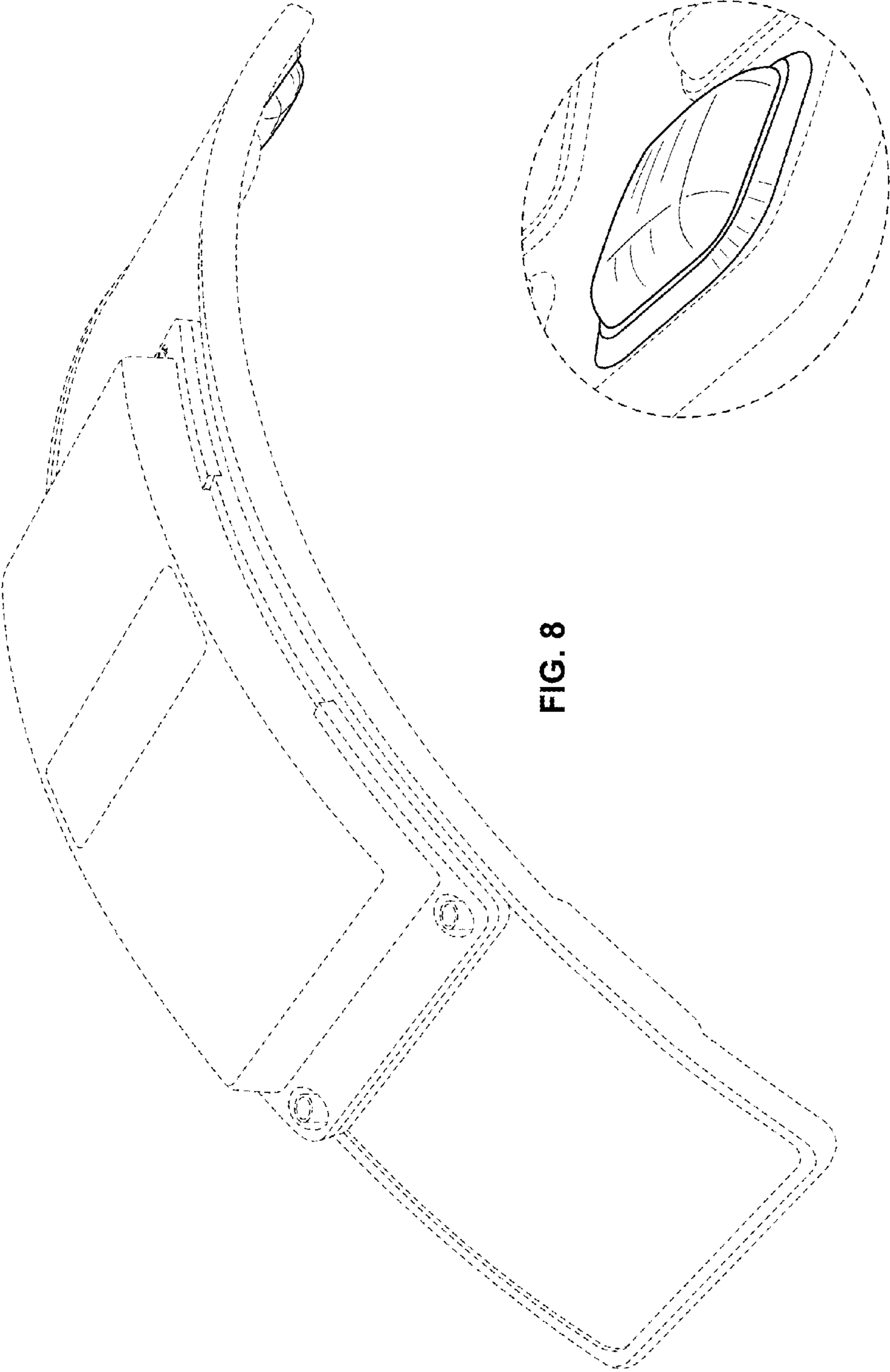


FIG. 8

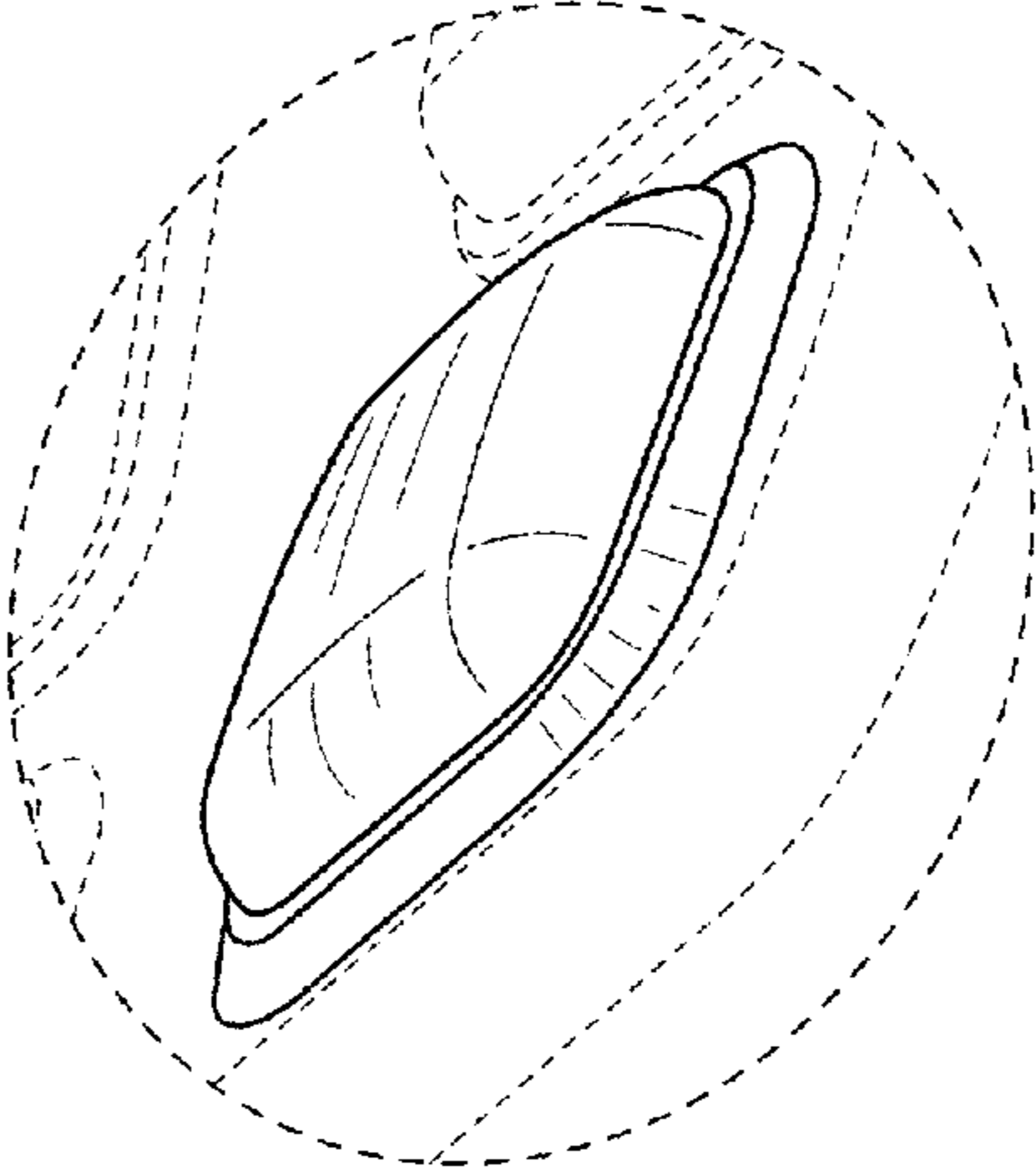


FIG. 9